

EAST Search History

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L1	5030	(thermo\$1electric near2 module)	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:10
L2	383	(thermo\$1electric near2 module) with (cool\$3 or heat\$3) with (semiconductor)	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:10
L3	267	2 and (@ad or @rlad) < "20040301"	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:11
L4	384	((thermo\$1electric\$3 or termal\$1electric\$3) near2 module) with (cool\$3 or heat\$3) with (semiconductor)	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:16
L5	8	4 and ((SiC or carbide or diamond) with thermo\$1electric)	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:17
L6	54	((thermo\$1electric\$3 or termal\$1electric\$3) near2 module) with (cool\$3 or heat\$3) and ((thermo\$1electric or module) with (carbide or SiC or diamond))	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:18
L7	32	6 and (@ad or @rlad) < "20040301"	US-PGRUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:19

L8	68	((thermo\$1electric\$3 or termal\$1electric\$3) near2 module) with (cool\$3 or heat\$3) and ((carbide or SiC) with (diamond or C))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:27
L9	48	8 and (@ad or @rlad) < "20040301"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:27
L10	135	((thermo\$1electric\$3 or termal\$1electric\$3) near2 (element or module)) with (cool\$3 or heat\$3) and ((carbide or SiC) with (diamond or C))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:35
L11	86	10 and (@ad or @rlad) < "20040301"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:35
L12	136	((thermo\$1electric\$3 or termal\$1electric\$3) near2 (element or module)) with (cool\$3 or heat\$3) and ((spring helix coil) with (shape or pattern))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:42
L13	109	12 and (@ad or @rlad) < "20040301"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:47
L16	37	13 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:49
L17	736	((thermo\$1electric\$3 or termal\$1electric\$3) near2 (element or module)) with (cool\$3 or heat\$3) and (thermo\$1electric with (shape or pattern))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:52

L18	484	17 and (@ad or @rlad) < "20040301"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:53
L19	11	18 and ((SiC or carbide or diamond) with thermo\$electric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:53
L20	63	18 and ((dense or density) with thermo\$electric)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 10:55
L21	9	("5715684" "6000225" "6230497" "6250085" "6282907" "6396700" "6424533" "6489551" "6548894").PN. OR ("6804966").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/09 14:00
L22	7	("5181214" "5542018" "5832015" "6053640" "6146025").PN. OR ("6721341").URPN.	US-PGPUB; USPAT; USOCR	OR	ON	2008/11/09 14:07
L23	3	((thermo\$electric\$3 or termal\$electric\$3) near2 (element or module)) with (cool\$3 or heat\$3) and (((silicon near carbide) or SiC) with diamond with combination)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/09 14:26
S38	8	(US-20050086948-\$.did. or (US-7164077-\$ or US-6893902-\$ or US-6727422-\$ or US-6573596-\$ or US-6230497-\$ or US-6098408-\$ or US-5740016-\$.did.	US-PGPUB; USPAT	OR	ON	2008/11/05 10:35
S39	3	(S38 and (SiC or carbide or diamond))	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 10:36

S40	27031	(thermo\$1electric or thermo\$1element) with (cool\$3 or heat\$3)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 10:39
S41	8932	S40 and semiconductor	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 10:40
S42	340	S41 and ((SiC or carbide) with diamond)	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 10:40
S43	289	S42 and ((@ad or @rlad) < "20040301")	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 10:41
S44	4	2003/0067064	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 16:51
S45	2	"20030067064"	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/05 16:51
S46	4117	257/717-720.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/06 13:11
S47	2054	174/16.3.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/06 13:11

S48	286	228/222.ccls.	US-PGPUB; USPAT; USOCR; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2008/11/06 13:11
-----	-----	---------------	-------------------------------------------------------------------	----	----	---------------------

11/ 9/ 2008 4:03:21 PM

C:\Documents and Settings\Akalam\My Documents\EAST\Workspaces\10790298.wsp